

Lenovo System x 3100 M5 server (5457F3G)

System x 3100 M5 - Xeon 4C E3-1271 v3 80W 3.6GHz/1600MHz/8MB, 1x4GB, O/Bay HS 2.5in SATA, SR M1115, Multi-burner, 430W p/s, Tower



Price details:

Price excl. VAT: 1,289.10 €

Eco fees: 0.07 €

VAT 21 %: 270.73 €

Product details:

Product code: 5457F3G

EAN: 5051045192712

Manufacturer: Lenovo

PDF generated on: 23 February, 2018



1,559.90 €

* VAT included

Business-class reliability, performance, and energy efficiency in a compact tower

The new single-socket IBM® System x3100 M5 server provides business-class reliability and performance in a compact tower, optimized for small to medium-sized businesses and distributed environments. Equipped with the latest Intel Xeon E3-1200 v3 processors, USB 3.0 for fast data transfer, 1.35 V low-voltage memory for power savings, 3.5-inch hot-swap SAS hard disk drives (HDDs) for minimized downtime, and four levels of RAID for enhanced data protection, the x3100 M5 brings new levels of performance to your workloads while maximizing energy savings. This efficient tower meets your business needs today and offers upgrade potential when your requirements grow.

Reliability and performance in a flexible, compact tower server

Whether your workloads include basic infrastructure, web server, or file and print, the x3100 M5 delivers. Choose your storage preference from models with four 3.5-inch simple-swap HDD bays, or get the hot-swap versatility of eight 2.5-inch bays or four 3.5-inch hot-swap bays. Standard features include capacity for up to 32 GB of memory, two Gigabit Ethernet ports, and two front-mounted fast USB 3.0 ports, plus multiple internal and external USB 2.0 connections. Business-class reliability features—such as standard RAID, basic light path diagnostics, and optional redundant power supplies and fans—protect your data and facilitate outstanding uptime for your business at great value. And no matter the model, every configuration incorporates IBM quality.

Main specifications:

Processor

| | |
|---|----------------------|
| Processor frequency: | 3.6 GHz |
| Processor family: | Intel Xeon E3 v3 |
| Processor model: | E3-1271V3 |
| Processor cores: | 4 |
| Number of processors installed: | 1 |
| Processor cache type: | Smart Cache |
| Processor cache: | 8 MB |
| System bus rate: | 5 GT/s |
| Processor manufacturer: | Intel |
| Processor socket: | LGA 1150 (Socket H3) |
| Processor boost frequency: | 4 GHz |
| Processor lithography: | 22 nm |
| Processor threads: | 8 |
| Processor operating modes: | 32-bit,64-bit |
| Stepping: | C0 |
| FSB Parity: | N |
| Bus type: | DMI2 |
| Processor codename: | Haswell |
| Maximum internal memory supported by processor: | 32GB |

| | |
|--|-----------------------|
| Memory types supported by processor: | DDR3-SDRAM |
| Memory clock speeds supported by processor: | 1333,1600 MHz |
| Memory bandwidth supported by processor (max): | 25.6 GB/s |
| Memory channels supported by processor: | Dual |
| ECC supported by processor: | Y |
| Execute Disable Bit: | Y |
| Idle States: | Y |
| Thermal Monitoring Technologies: | Y |
| Maximum number of PCI Express lanes: | 16 |
| PCI Express configurations: | 1x16,2x8,1x8+2x4 |
| Processor package size: | 37.5 mm |
| Supported instruction sets: | AVX 2.0 |
| Scalability: | 1S |
| Embedded options available: | N |
| Thermal solution specification: | PCG 2013D |
| Graphics & IMC lithography: | 22 nm |
| Thermal Design Power (TDP): | 80 W |
| Processor series: | Intel Xeon E3-1200 v3 |
| Conflict Free processor: | N |

Memory

| | |
|-------------------------------|------------|
| Internal memory: | 4 GB |
| Internal memory type: | DDR3-SDRAM |
| Maximum internal memory: | 32 GB |
| Memory slots: | 4x UDIMM |
| Memory clock speed: | 1600 MHz |
| ECC: | Y |
| Memory layout (slots x size): | 1 x 4 GB |

Storage

| | |
|---------------------------|---------------------------------------|
| Hard drive size: | 2.5 " |
| Hard drive interface: | Serial ATA,Serial Attached SCSI (SAS) |
| RAID support: | Y |
| Maximum storage capacity: | 4 TB |
| Hot-Plug support: | Y |
| Internal drive bays: | 4 |

Graphics

| | |
|----------------------------------|---------------|
| On-board graphics adapter: | N |
| On-board graphics adapter model: | Not available |

Networking

| | |
|---------------|---|
| Ethernet LAN: | Y |
| Wi-Fi: | N |

Ports & interfaces

| | |
|--|---|
| USB 2.0 ports quantity: | 4 |
| Ethernet LAN (RJ-45) ports: | 2 |
| USB 3.0 (3.1 Gen 1) Type-A ports quantity: | 2 |

Expansion slots

| | |
|----------------------------------|-----|
| PCI Express x4 (Gen 3.x) slots: | 1 |
| PCI Express x8 (Gen 3.x) slots: | 1 |
| PCI Express x16 (Gen 3.x) slots: | 1 |
| PCI Express slots version: | 3.0 |

Design

| | |
|---------------------|-----------------|
| Chassis type: | Tower |
| Optical drive type: | DVD Super Multi |

Performance

| | |
|-------------------------------|---|
| Operating system installed: | N |
| Compatible operating systems: | Microsoft Windows Server 2012/2008/R2, SBS 2011, Red Hat Enterprise Linux, SUSE Linux, VMware |

Processor special features

| | |
|--|---|
| CPU configuration (max): | 1 |
| Intel Rapid Storage Technology: | N |
| Enhanced Intel SpeedStep Technology: | Y |
| Intel® Identity Protection Technology (Intel® IPT): | |
| Intel® Wireless Display (Intel® WiDi): | N |
| Intel Virtualization Technology for Directed I/O (VT-d): | Y |

| | |
|--|-------|
| Intel® Anti-Theft Technology (Intel® AT): | Y |
| Intel® Hyper Threading Technology (Intel® HT Technology): | Y |
| Intel® My WiFi Technology (Intel® MWT): | N |
| Intel® Turbo Boost Technology: | Y |
| Intel® vPro® Technology: | Y |
| Intel® Quick Sync Video Technology: | Y |
| Intel® InTru® 3D Technology: | N |
| Intel® Clear Video HD Technology (Intel® CVT HD): | N |
| Intel® Insider®: | N |
| Intel Flex Memory Access: | Y |
| Intel® Smart Cache: | Y |
| Intel® AES New Instructions (Intel® AES-NI): | Y |
| Intel Trusted Execution Technology: | Y |
| Intel Enhanced Halt State: | Y |
| Intel VT-x with Extended Page Tables (EPT): | Y |
| Intel Demand Based Switching: | N |
| Intel® Secure Key: | Y |
| Intel Stable Image Platform Program (SIPP): | Y |
| Intel Clear Video Technology: | N |
| Intel® Clear Video Technology for Mobile Internet Devices (Intel CVT for MID): | N |
| Intel 64: | Y |
| Intel Identity Protection Technology version: | 1.00 |
| Intel Stable Image Platform Program (SIPP) version: | 1.00 |
| Intel Secure Key Technology version: | 1.00 |
| Intel Virtualization Technology (VT-x): | Y |
| Intel TSX-NI version: | 1.00 |
| Intel Dual Display Capable Technology: | N |
| Intel FDI Technology: | N |
| Intel I/O Acceleration Technology: | Y |
| Intel Fast Memory Access: | Y |
| Processor ARK ID: | 80908 |

Power

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|---------------------------------------|-------|
| Redundant power supply (RPS) support: | Y |
| Power supply: | 430 W |
| Number of main power supplies: | 2 |

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